

Oct. 22-25 Taipei Nangang Exhibition Center, Hall 1

IMPACT Conference Call for papers is now open!
Submit your abstract before June 23rd

Call for Papers

Join us at IMPACT 2024, the premier conference for PCB and packaging professionals in Taiwan, organized by IEEE-EPS-Taipei, iMAPS-Taiwan, ITRI, and TPCA. This year's event will be held from Oct. 22nd-25th at Taipei Nangang Exhibition Center, in conjunction with TPCA Show 2024. The symposium will focus on the theme "IMPACT on Sustainable Technology", exploring the latest electronic technologies and fostering collaboration among enterprises and organizations.

As artificial intelligence, quantum computing, and low-earth orbit satellite communications rapidly advance, the convergence of technology and resource sustainability becomes an increasingly urgent strategic imperative. IMPACT 2024 will delve into these technological innovations and sustainability advancements in PCB and packaging, offering professional development courses, plenary speeches, special sessions, industrial sessions, invited talks, outstanding papers, and poster presentations. This conference also collaborates with international organizations such as ICEP and JIEP from Japan, iNEMI and IEEE EPS from the USA, and global consulting companies like Yole Développement and Techsearch from the USA. Join us at IMPACT 2024 to be part of the future of electronics technology!

【Date】 Oct. 22nd (Tue)-25th (Fri), 2024

【Venue】 Taipei Nangang Exhibition Center

【Theme】 IMPACT on Sustainable Technology

**【Exhibition】 TPCA Show, TAITRONICS,
OPTO TAIWAN, AIoT Taiwan**

【On-line Submission】 www.impact.org.tw

IMPORTANT DATE

Item	Date	Remark
Abstract Submission Deadline	Jun. 23	400-500 words, 1-2 pages Submit online www.impact.org.tw
Abstract Acceptance Notification	Jul. 17	Notice sent via email
Advanced Program Online	Aug. 14	Advanced program announcement
Full Paper Submission Deadline	Aug. 25	4 pages including figures and tables Submit on-line through the conference website

SCOPE OF PAPER SOLICITED

Packaging

- P1. Advanced Packaging Technologies
- P2. Power Electronics Packaging
- P3. Interconnections & Nanotechnology
- P4. Design, Modeling, AI/Machine Learning Applications, and Testing
- P5. Advanced Materials, Automatic Process & Assembly
- P6. Emerging Systems Packaging Technologies
- P7. Sustainable Technologies & Systems

PCB

- B1. Advanced and Green Materials and Process
- B2. Test, Quality, Inspection and Reliability
- B3. HDI, IC Substrate and FPC Technology
- B4. Smart Manufacturing and Automation

- * Papers relevant to the above scopes are encouraged to submit but NOT limited to.
- * Conference organizer keeps the right to finalize session arrangement.
- * Authors of accepted papers including oral presentations and posters should register before the deadline; please be noted that unregistered (paid) papers will be removed from the conference program.
- * The organizer reserves the right to modify the agenda.

PAPER AWARD

Outstanding Paper Award will be elected by IMPACT Technical Program Committee from student and industrial papers respectively. The paper awardees will be announced and honored next year.
Evaluation criteria: Originality, Completeness, Significance, Industrial merit of the abstract, full paper, and presentation.

SPONSOR

IMPACT 2024 sponsors can improve the corporate image, enhance professional development, create networking opportunities and enjoy exclusive benefits. There are multiple sponsorship packages for you to choose!

CONTACT

IMPACT 2024 Secretariat:
Taiwan Printed Circuit Association (TPCA)
Tel: +886-3-3815659 #407 Cindy #405 Mickey #404 Sophia
Fax: +886-3-3815150
Email: service@impact.org.tw
[http:// www.impact.org.tw](http://www.impact.org.tw)



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